

Abstract of the Disclosure

In the probe card of the semiconductor device measurement device, measurement is to be done in the stability without damage beyond the needle diameter on the pad of the wafer by the probe needle. The straight probe needle 5 is inserted in the upper guide plate 2, the rotary guide plate 3 and the bottom guide plate 4. The rotary guide plate 3 is a little displaced, and the center of the probe needle 5 is bent. Under this condition, the stage with the wafer thereon is raised, and then the tip of the probe needle 5 reaches the pad on the surface of the wafer. The rotary guide plate 3 has a guide slot 7. The probe needle 5 reaches the pad in the horizontal plane. The fixed guide pin 8 moves along the guide slot 7. The rotary guide plate 3 is moved swinging. The probe needle 5 breaks through the natural oxide film stuck on the pad. In this way, the dispersion of the pressure of the probe needle 5 is prevented. Measurement can be done without damage beyond the needle diameter on the pad of the wafer. Moreover, the pitch of the probe needle 5 can be narrow, and assembling becomes easy.